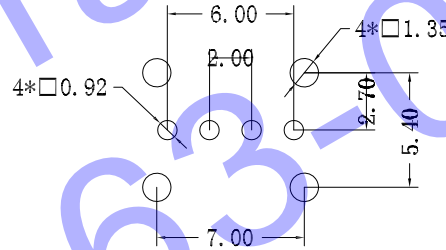
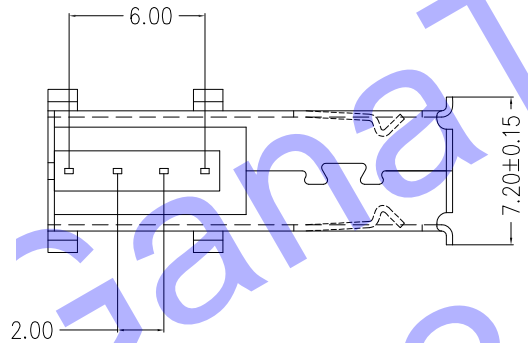
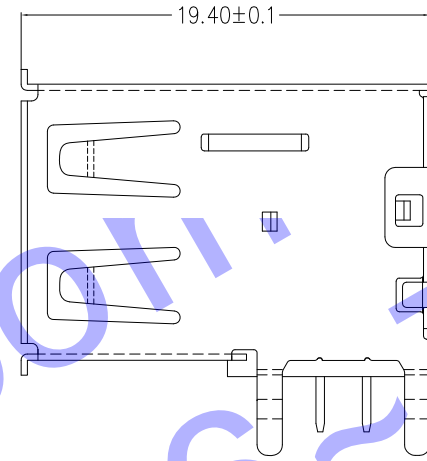
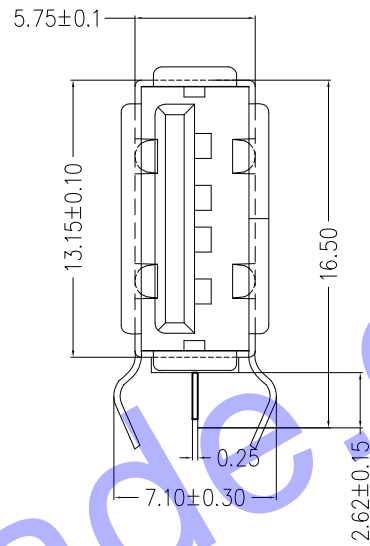
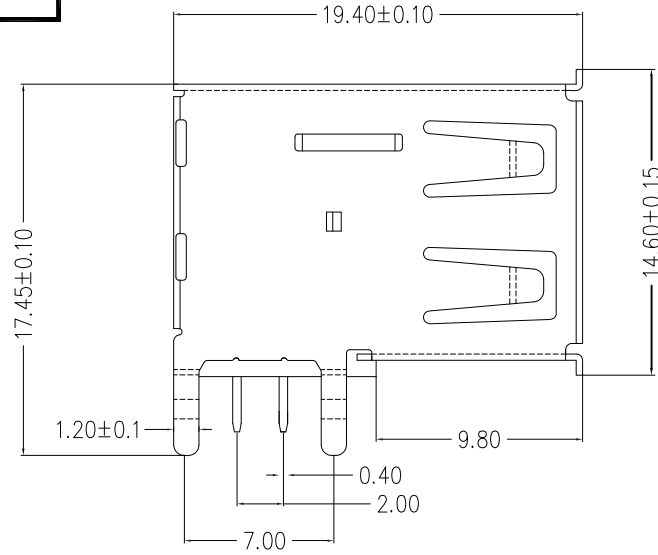


HSF



PCB.LAYOUT

特性:Specifications:

电器:Electrical:

接触阻抗:Contact Resistance

30 milliohms MAX

耐电压:Dielectric Withstanding Voltage:

500V AC AT Sea Level

绝缘阻抗:Insulation Resistance:

100 MEGA ohms MIN

材料:Material:

塑胶:PBT

端子:Contact:Copper Alloy C2680H

铜壳/铁壳:Shell: Copper Alloy C2680H/Spcc

电镀:Finish:

端子:Contact: Plated Gold in Mating Area;

Tin/ On Solder Tails

接触点镀金.脚镀锡

铜壳/铁壳:Shell:

Nickel Plating

镀镍

				OPERATION	DRAW	DATE	SCALE	FIT	PART NO.	HDC 有限公司
				X.X ±0.40	JYHuang	2012/06/29	UNIT	mm	USB-0S0RAG00	
				X.XX ±0.25	CHECK	DATE	SIZE	A4	TITLE:	
				X.XXX ±0.15	APPROVE	DATE	SHEET	1/1	USB2.0 A TYPE 90度 侧插入	
A0	2012/06/29	NEW		Angle ± 3°			PROJ.	Customer NO.		
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	DIM TOL						

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USB2.0 A TYPE 90度 侧插入